

Title (en)  
PRINTED CIRCUIT BOARD

Title (de)  
LEITERPLATTE

Title (fr)  
CARTE DE CIRCUITS IMPRIMÉS

Publication  
**EP 2916629 B1 20180606 (EN)**

Application  
**EP 14854898 A 20140114**

Priority  
JP 2014050431 W 20140114

Abstract (en)  
[origin: EP2916629A1] A printed wiring board (10) includes: an inner layer structure body (20) containing at least an inner layer insulative base material (31) composed of a glass cloth (31a) and resin (31b) which covers the glass cloth (31a) and not containing a resin insulative base material composed only of resin; outer layer wiring (21) formed on a first face (20a) of the inner layer structure body (20); and a solder resist layer (23) formed on a surface of the outer layer wiring (21), wherein in the inner layer structure body (20), an opening part (11) is formed, and the solder resist layer (23) is composed of a first ink part (23a) covering at least the outer layer wiring (21) that is formed on a partial region of the first face (20a) which corresponds to the opening part (11) and a second ink part (23b) interposing both ends of the first ink part (23a) and being lower in flexibility than the first ink part (23a).

IPC 8 full level  
**H05K 1/02** (2006.01); **H05K 3/28** (2006.01); **H05K 3/46** (2006.01)

CPC (source: EP KR US)  
**H05K 1/028** (2013.01 - US); **H05K 1/0281** (2013.01 - EP US); **H05K 3/282** (2013.01 - EP US); **H05K 3/4626** (2013.01 - KR); **H05K 3/4664** (2013.01 - KR); **H05K 3/4691** (2013.01 - EP KR US); **H05K 1/024** (2013.01 - EP US); **H05K 1/025** (2013.01 - EP US); **H05K 1/0278** (2013.01 - EP US); **H05K 3/0044** (2013.01 - EP US); **H05K 3/4652** (2013.01 - EP US); **H05K 2201/0187** (2013.01 - EP US); **H05K 2201/0191** (2013.01 - EP US); **H05K 2203/0207** (2013.01 - EP US); **H05K 2203/0228** (2013.01 - EP US)

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**EP 2916629 A1 20150909**; **EP 2916629 A4 20160713**; **EP 2916629 B1 20180606**; CN 104919907 A 20150916; CN 109890131 A 20190614; CN 109890131 B 20210914; JP 5684958 B1 20150318; JP WO2015079713 A1 20170316; KR 101569156 B1 20151113; KR 20150095234 A 20150820; TW 201536123 A 20150916; TW I538577 B 20160611; US 2015373829 A1 20151224; US 9326376 B2 20160426; WO 2015079713 A1 20150604

DOCDB simple family (application)  
**EP 14854898 A 20140114**; CN 201480003806 A 20140114; CN 201910270908 A 20140114; JP 2014050431 W 20140114; JP 2014534296 A 20140114; KR 20157008371 A 20140114; TW 103143794 A 20141216; US 201414649204 A 20140114